

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claims 1-19 (Cancelled).

Claims 20-83 (Previously cancelled).

84. (New) An electronic interconnect element comprising:  
a first leaf portion;  
a contact tip located on a first surface of the first leaf portion; and  
at least one support point coupled to an opposite surface of the first leaf portion in such a relationship to the contact tip that the first leaf portion acts as a spring when the contact tip engages a contact feature of an electronic device and urges the contact tip against the contact feature substantially without wiping.
85. (New) The electronic interconnect element of claim 84, wherein the leaf portion is formed lithographically.
86. (New) The electronic interconnect element of claim 84, wherein the contact tip is formed by a process of plating into an opening in a substrate.
87. (New) The electronic interconnect element of claim 86, wherein the substrate is silicon.
88. (New) The electronic interconnect element of claim 86, wherein the substrate is a metal.
89. (New) The electronic interconnect element of claim 86, wherein the substrate is a ceramic.
90. (New) The electronic interconnect element of claim 86, wherein the substrate is an organic.
91. (New) The electronic interconnect element of claim 84, wherein the first leaf portion is a beam.
92. (New) The electronic interconnect element of claim 91, wherein the beam is rectangular.
93. (New) The electronic interconnect element of claim 84, wherein the first leaf portion is a generally planar support plate.
94. (New) The electronic interconnect element of claim 93, wherein the support plate is disc-shaped.
95. (New) The electronic interconnect element of claim 93, wherein the support plate is rectangular.

96. (New) The electronic interconnect element of claim 93, wherein the support plate has a hole therethrough.
97. (New) The electronic interconnect element of claim 93, wherein the support plate is shaped such that a middle portion is stressed in a torsional manner.
98. (New) A probe card comprising a plurality of electronic interconnect elements as recited in claim 84 for contacting contact features on an electronic device.
99. (New) A space transformer comprising a plurality of electronic interconnect elements as recited in claim 84.
100. (New) The probe card of claim 98, wherein the contact tips of the electronic interconnect elements do not wipe across the contact features of the electronic device.
101. (New) A method of making an electronic interconnect element comprising the steps of:  
providing a plurality of leaf portions;  
locating a contact tip on a first surface of one of the plurality of leaf portions; and  
coupling at least one support point between an opposite surface of the one leaf portion and another of the plurality of leaf portions in such a relationship to the contact tip that the plurality of leaf portions act as a spring when the contact tip engages a contact feature of an electronic device and urge the contact tip against the contact feature substantially without wiping.
102. (New) An electronic interconnect element comprising:  
a first leaf portion;  
a contact tip located on a first side of the first leaf portion;  
at least one first support point coupled to an opposite side of the first leaf portion offset from the contact tip;  
a second leaf portion having a first side coupled to the at least one first support point; and  
at least one second support point coupled to an opposite side of the second leaf portion offset from the at least one first support point.
103. (New) The electronic interconnect element of claim 102, wherein the contact tip and the second support point are located on a common axis.
104. (New) The electronic interconnect element of claim 102 further comprising a third support point spaced apart from the first support point and coupled to the opposite side of the first leaf portion offset from the contact tip, and a fourth support point spaced apart from the second support point and coupled to the opposite side of the second leaf portion offset from the first contact point.
105. (New) The electronic interconnect element of claim 102 further comprising a third leaf portion having a first side coupled to the second support point, and a third support point coupled to an opposite side of the third leaf portion offset from the second support point.

106. (New) The electronic interconnect element of claim 102 wherein the contact tip, the first and second leaf portions and the first and second support points are structurally distinct elements that are joined one to another.
107. (New) An electronic interconnect element comprising:
- a plurality of leaf portions;
  - a contact tip located on a first side of one of the plurality of leaf portions;
  - at least one first support point coupled to an opposite side of the one leaf portion offset from the contact tip;
  - another of the plurality of leaf portions having a first side coupled to the at least one first support point; and
  - at least one second support point coupled to an opposite side of the other leaf portion offset from the at least one first support point.